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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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## SMCG-HR Series



### Agency Approvals

AGENCY	AGENCY FILE NUMBER
	E230531

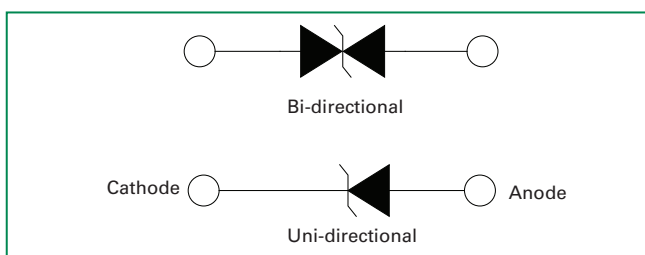
### Maximum Ratings and Thermal Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak Pulse Power Dissipation at $T_A=25^\circ\text{C}$ by 10/1000 $\mu\text{s}$ waveform (Fig.2)(Note 1), (Note 2)	$P_{PPM}$	1500	W
Power Dissipation on infinite heat sink at $T_A=50^\circ\text{C}$	$P_{M(AV)}$	6.5	W
Peak Forward Surge Current, 8.3ms Single Half Sine Wave (Note 3)	$I_{FSM}$	200	A
Maximum Instantaneous Forward Voltage at 100A for Unidirectional only	$V_F$	3.5	V
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-65 to 150	$^\circ\text{C}$
Typical Thermal Resistance Junction to Lead	$R_{wJL}$	15	$^\circ\text{C/W}$
Typical Thermal Resistance Junction to Ambient	$R_{wJA}$	75	$^\circ\text{C/W}$

**Notes:**

1. Non-repetitive current pulse, per Fig. 4 and derated above  $T_A = 25^\circ\text{C}$  per Fig. 3.
2. Mounted on copper pad area of 0.31x0.31" (8.0 x 8.0mm) to each terminal.
3. Measured on 8.3ms single half sine wave or equivalent square wave for unidirectional device only, duty cycle=4 per minute maximum.

### Functional Diagram



### Description

The SMCG-HR series is designed specifically to protect sensitive electronic equipment from voltage transients induced by lightning and other transient voltage events.

### Features


- High-Reliability up-screened for critical applications require higher reliability performance and low infant mortality failures.
- Excellent clamping capability
- Low incremental surge resistance
- Typical  $I_R$  less than  $1\mu\text{A}$  above 12V
- For surface mounted applications to optimize board space
- L bend lead forming gives best solderability for Hi reliability application
- Typical failure mode is short from over-specified voltage or current
- Whisker test is conducted based on JEDEC JESD201A per its table 4a and 4c
- IEC-61000-4-2 ESD 15kV(Air), 8kV (Contact)
- ESD protection of data lines in accordance with IEC 61000-4-2 (IEC801-2)
- EFT protection of data lines in accordance with IEC 61000-4-4 (IEC801-4)
- Built-in strain relief
- Fast response time: typically less than 1.0ps from 0V to BV min
- 1500W peak pulse power capability at 10/1000 $\mu\text{s}$  waveform, repetition rate (duty cycles):0.01%
- $V_{BR} @T_J = V_{BR} @25^\circ\text{C} \times (1 + \alpha T \times (T_J - 25))$  ( $\alpha T$ :Temperature Coefficient, typical value is 0.1%)
- Glass passivated chip junction
- High temperature soldering guaranteed: 260 $^\circ\text{C}$ /10 seconds at terminals
- Meet MSL level1, per J-STD-020, LF maximum peak of 260 $^\circ\text{C}$
- Matte tin lead-free plated
- Halogen free
- RoHS compliant with exemption 7a and 7c-I
- 2nd level interconnect is Pb-free per IPC/JEDEC J-STD-609A.01

### Applications

TVS devices are ideal for the protection of I/O Interfaces,  $V_{CC}$  bus and other vulnerable circuits used in Telecom, Computer, Industrial and Consumer electronic applications.



### Electrical Characteristics

Part Number (Uni)	Part Number (Bi)	Marking		Reverse Stand off Voltage $V_R$ (Volts)	Breakdown Voltage $V_{BR}$ (Volts) @ $I_T$		Test Current $I_T$ (mA)	Maximum Clamping Voltage $V_C$ @ $I_{pp}$ (V)	Maximum Peak Pulse Current $I_{pp}$ (A)	Maximum Reverse Leakage $I_R$ @ $V_R$ ( $\mu$ A)	Agency Approval 
		UNI	BI		MIN	MAX					
SMCG5.0A-HR	SMCG5.0CA-HR	GDE	BDE	5.0	6.40	7.00	10	9.2	163.0	800	X
SMCG6.0A-HR	SMCG6.0CA-HR	GDG	BDG	6.0	6.67	7.37	10	10.3	145.7	800	X
SMCG6.5A-HR	SMCG6.5CA-HR	GDK	BDK	6.5	7.22	7.98	10	11.2	134.0	500	X
SMCG7.0A-HR	SMCG7.0CA-HR	GDM	BDM	7.0	7.78	8.60	10	12.0	125.0	200	X
SMCG7.5A-HR	SMCG7.5CA-HR	GDP	BDP	7.5	8.33	9.21	1	12.9	116.3	100	X
SMCG8.0A-HR	SMCG8.0CA-HR	GDR	BDR	8.0	8.89	9.83	1	13.6	110.3	50	X
SMCG8.5A-HR	SMCG8.5CA-HR	GDT	BDT	8.5	9.44	10.40	1	14.4	104.2	20	X
SMCG9.0A-HR	SMCG9.0CA-HR	GDV	BDV	9.0	10.00	11.10	1	15.4	97.4	10	X
SMCG10A-HR	SMCG10CA-HR	GDX	BDX	10.0	11.10	12.30	1	17.0	88.3	5	X
SMCG11A-HR	SMCG11CA-HR	GDZ	BDZ	11.0	12.20	13.50	1	18.2	82.5	1	X
SMCG12A-HR	SMCG12CA-HR	GEE	BEE	12.0	13.30	14.70	1	19.9	75.4	1	X
SMCG13A-HR	SMCG13CA-HR	GEG	BEG	13.0	14.40	15.90	1	21.5	69.8	1	X
SMCG14A-HR	SMCG14CA-HR	GEK	BEK	14.0	15.60	17.20	1	23.2	64.7	1	X
SMCG15A-HR	SMCG15CA-HR	GEM	BEM	15.0	16.70	18.50	1	24.4	61.5	1	X
SMCG16A-HR	SMCG16CA-HR	GEP	BEP	16.0	17.80	19.70	1	26.0	57.7	1	X
SMCG17A-HR	SMCG17CA-HR	GER	BER	17.0	18.90	20.90	1	27.6	54.4	1	X
SMCG18A-HR	SMCG18CA-HR	GET	BET	18.0	20.00	22.10	1	29.2	51.4	1	X
SMCG20A-HR	SMCG20CA-HR	GEV	BEV	20.0	22.20	24.50	1	32.4	46.3	1	X
SMCG22A-HR	SMCG22CA-HR	GEX	BEX	22.0	24.40	26.90	1	35.5	42.3	1	X
SMCG24A-HR	SMCG24CA-HR	GEZ	BEZ	24.0	26.70	29.50	1	38.9	38.6	1	X
SMCG26A-HR	SMCG26CA-HR	GFE	BFE	26.0	28.90	31.90	1	42.1	35.7	1	X
SMCG28A-HR	SMCG28CA-HR	GFG	BFG	28.0	31.10	34.40	1	45.4	33.1	1	X
SMCG30A-HR	SMCG30CA-HR	GFK	BFK	30.0	33.30	36.80	1	48.4	31.0	1	X
SMCG33A-HR	SMCG33CA-HR	GFM	BFM	33.0	36.70	40.60	1	53.3	28.2	1	X
SMCG36A-HR	SMCG36CA-HR	GFP	BFP	36.0	40.00	44.20	1	58.1	25.9	1	X
SMCG40A-HR	SMCG40CA-HR	GFR	BFR	40.0	44.40	49.10	1	64.5	23.3	1	X
SMCG43A-HR	SMCG43CA-HR	GFT	BFT	43.0	47.80	52.80	1	69.4	21.7	1	X
SMCG45A-HR	SMCG45CA-HR	GFV	BFV	45.0	50.00	55.30	1	72.7	20.6	1	X
SMCG48A-HR	SMCG48CA-HR	GFX	BFX	48.0	53.30	58.90	1	77.4	19.4	1	X
SMCG51A-HR	SMCG51CA-HR	GFZ	BFZ	51.0	56.70	62.70	1	82.4	18.2	1	X
SMCG54A-HR	SMCG54CA-HR	GGE	BGE	54.0	60.00	66.30	1	87.1	17.3	1	X
SMCG58A-HR	SMCG58CA-HR	GGG	BGG	58.0	64.40	71.20	1	93.6	16.1	1	X
SMCG60A-HR	SMCG60CA-HR	GGK	BGK	60.0	66.70	73.70	1	96.8	15.5	1	X
SMCG64A-HR	SMCG64CA-HR	GGM	BGM	64.0	71.10	78.60	1	103.0	14.6	1	X
SMCG70A-HR	SMCG70CA-HR	GGP	BGP	70.0	77.80	86.00	1	113.0	13.3	1	X
SMCG75A-HR	SMCG75CA-HR	GGR	BGR	75.0	83.30	92.10	1	121.0	12.4	1	X
SMCG78A-HR	SMCG78CA-HR	GGT	BGT	78.0	86.70	95.80	1	126.0	11.9	1	X
SMCG85A-HR	SMCG85CA-HR	GGV	BGV	85.0	94.40	104.00	1	137.0	11.0	1	X
SMCG90A-HR	SMCG90CA-HR	GGX	BGX	90.0	100.00	111.00	1	146.0	10.3	1	X
SMCG100A-HR	SMCG100CA-HR	GGZ	BGZ	100.0	111.00	123.00	1	162.0	9.3	1	X
SMCG110A-HR	SMCG110CA-HR	GHE	BHE	110.0	122.00	135.00	1	177.0	8.5	1	X
SMCG120A-HR	SMCG120CA-HR	GHG	BHG	120.0	133.00	147.00	1	193.0	7.8	1	X

Note:

1. For bidirectional type having  $V_R$  of 10 volts and less, the  $I_R$  limit is double.

### Screen Process

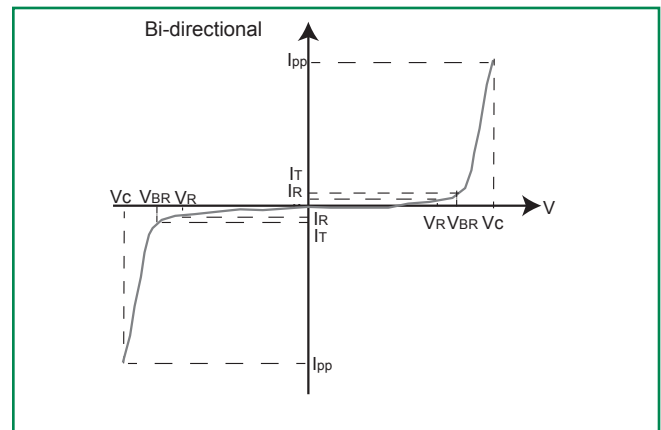
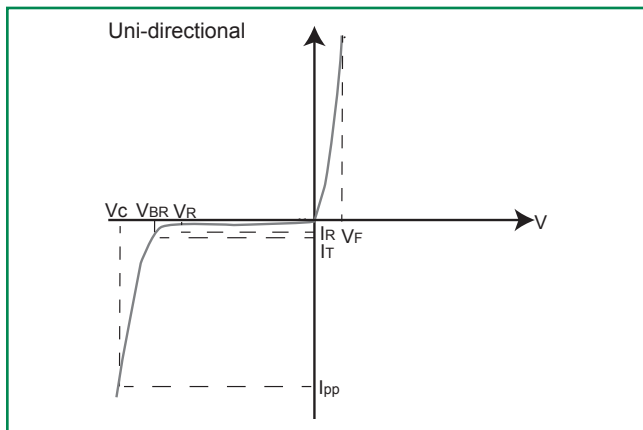
<b>100% vision inspection</b>	MIL-STD-750 method 2074
<b>100% High Temperature Storage Life (168hrs, 175C)</b>	MIL-STD-750 method 1031
<b>100% X-RAY inspection</b>	MIL-STD-750 method 2076
<b>100% Temperature cycle test (-55-150C, 20 cycles, dwell time 15 min)</b>	MIL-STD-750 method 1051
<b>100% Reflow (2x)</b>	JEDEC J-STD-020
<b>100% surge test (2x)</b>	MIL-STD-750 method 4066
<b>100% HTRB(150C, Bias=VR(80% breakdown voltage), 96hrs), for Bi-direction products, 96hrs for each direction</b>	MIL-STD-750 method 1038
<b>Final electrical test( 100% 3 sigma limit, 100% dynamic test and PAT limit)</b>	MIL-STD-750 method 4016.4021.4011

Note: Up-screen program can be specified by customer's request via contacting Littelfuse service

### Group B Test Requirement

Screen	Method	Condition	Requirement
Surge Test	10/1000 $\mu$ S Peak Pluse Waveform	Maximum Clamping Voltage ( $V_c$ ) @ Peak Plus Current ( $I_{pp}$ )	Sample Size 45 Perform 10x Accept 0 Failures
Burn - In (HTRB)	MIL - STD - 750, Method 1038.5	Applied Voltage 100% $V_R$ @ 150°C	Sample Size 45 For Unidirectional, 150C/ $V_R$ /340hours, for Bidirectional, 150C/ $V_R$ /680hrs(340hours for each direction) Accept 0 Failures
Electrical Tests	--	$I_R$ @ $V_R$ , $V_{BR}$ @ $I_T$	Sample Size 45 Accept 0 Failures

### I-V Curve Characteristics



**$P_{ppm}$  Peak Pulse Power Dissipation** – Max power dissipation

**$V_R$  Stand-off Voltage** – Maximum voltage that can be applied to the TVS without operation

**$V_{BR}$  Breakdown Voltage** – Maximum voltage that flows through the TVS at a specified test current ( $I_T$ )

**$V_c$  Clamping Voltage** – Peak voltage measured across the TVS at a specified  $I_{ppm}$  (peak impulse current)

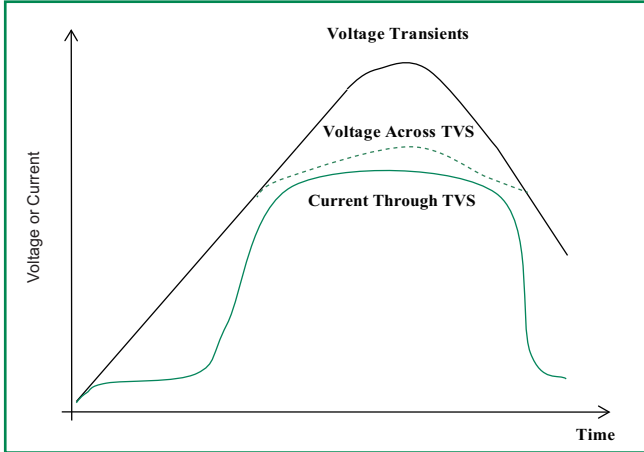
**$I_R$  Reverse Leakage Current** – Current measured at  $V_R$

**$V_F$  Forward Voltage Drop for Uni-directional**

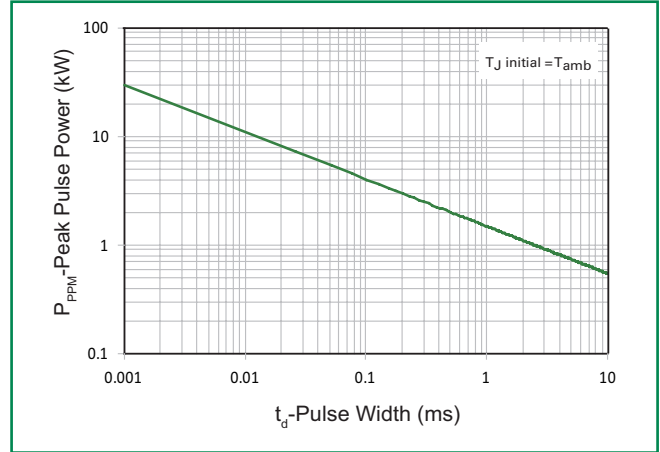
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**Ratings and Characteristic Curves** ( $T_A=25^\circ\text{C}$  unless otherwise noted)

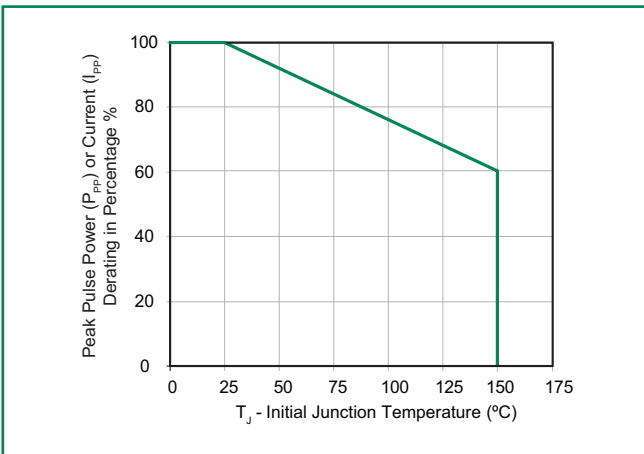
**Figure 1 - TVS Transients Clamping Waveform**



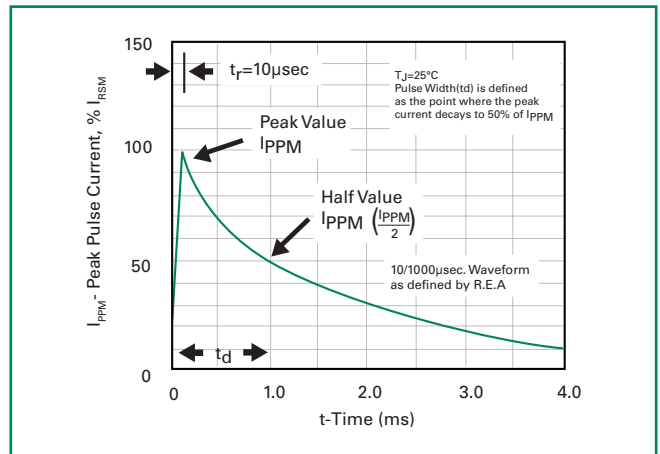
**Figure 2 - Peak Pulse Power Rating**



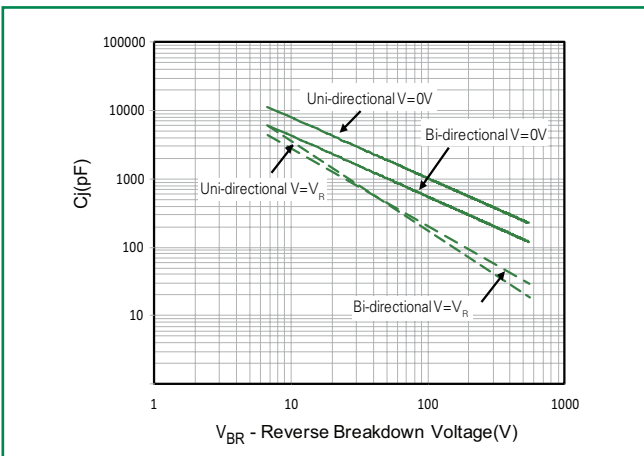
**Figure 3 - Peak Pulse Power Derating Curve**



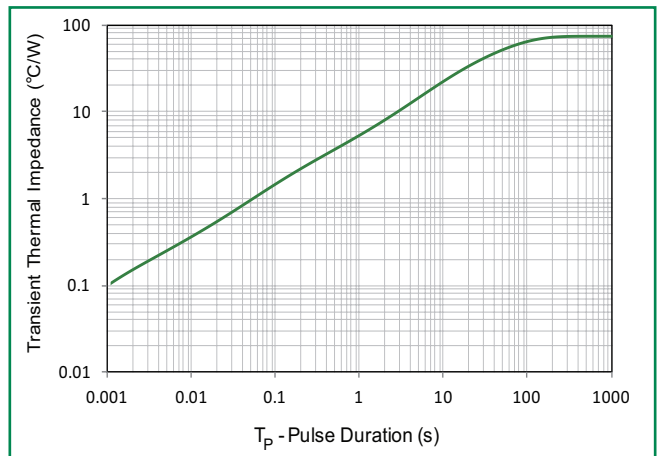
**Figure 4 - Pulse Waveform**



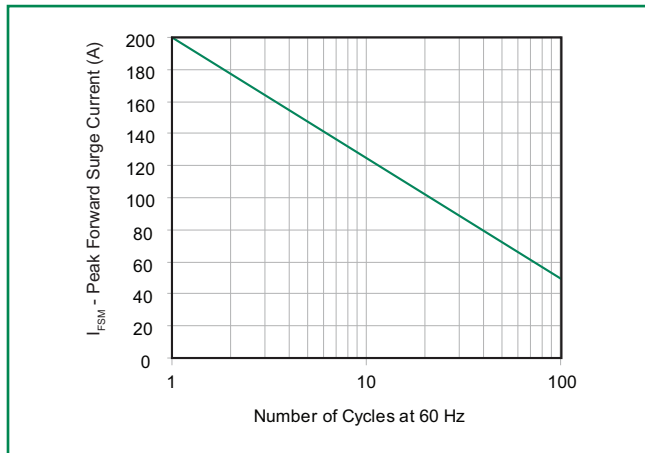
**Figure 5 - Typical Junction Capacitance**



**Figure 6 - Typical Transient Thermal Impedance**

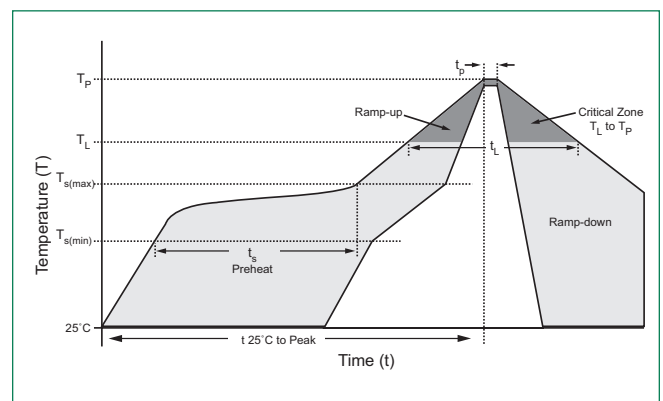


**Figure 7 - Maximum Non-Repetitive Peak Forward Surge Current Uni-Directional Only**



**Soldering Parameters**

Reflow Condition	Lead-free assembly	
Pre Heat	- Temperature Min ( $T_{s(min)}$ )	150°C
	- Temperature Max ( $T_{s(max)}$ )	200°C
	- Time (min to max) ( $t_s$ )	60 – 120 secs
Average ramp up rate (Liquidus Temp ( $T_L$ ) to peak)	3°C/second max	
$T_{s(max)}$ to $T_L$ - Ramp-up Rate	3°C/second max	
Reflow	- Temperature ( $T_L$ ) (Liquidus)	217°C
	- Time (min to max) ( $t_s$ )	60 – 150 seconds
Peak Temperature ( $T_p$ )	260 <sup>+0/-5</sup> °C	
Time within 5°C of actual peak Temperature ( $t_p$ )	30 seconds	
Ramp-down Rate	6°C/second max	
Time 25°C to peak Temperature ( $T_p$ )	8 minutes Max.	
Do not exceed	260°C	



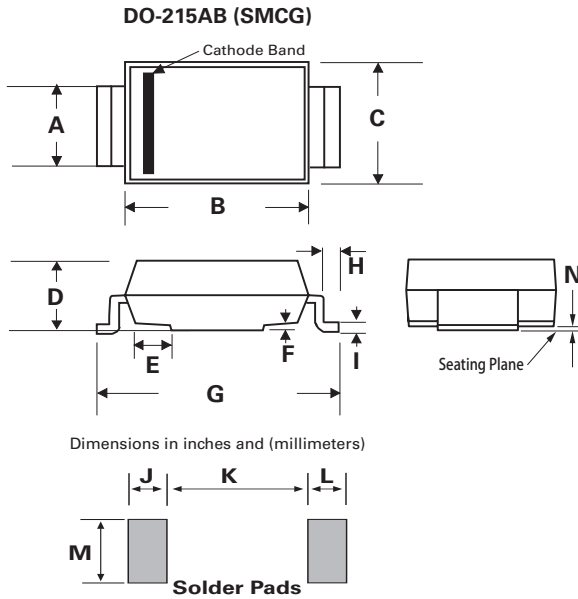
**Physical Specifications**

<b>Weight</b>	0.007 ounce, 0.21 grams
<b>Case</b>	JEDEC DO-215AB. Molded plastic body over glass passivated junction
<b>Polarity</b>	Color band denotes positive end (cathode) except Bidirectional.
<b>Terminal</b>	Matte Tin-plated leads, Solderable per JESD22-B102

**Environmental Specifications**

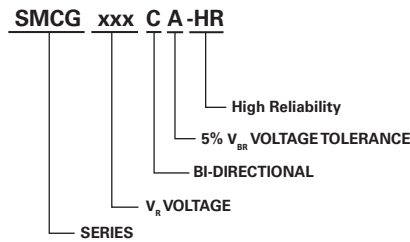
<b>High Temp. Storage</b>	JESD22-A103
<b>HTRB</b>	JESD22-A108
<b>Thermal Shock</b>	JESD22-A106
<b>MSL</b>	JEDEC-J-STD-020, Level 1
<b>H3TRB</b>	JESD22-A101
<b>RSH</b>	JESD22-A111

### Dimensions

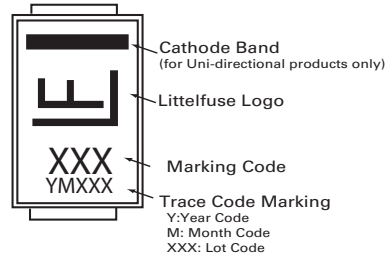


Dimensions	Inches		Millimeters	
	Min	Max	Min	Max
A	0.115	0.125	2.920	3.170
B	0.260	0.280	6.600	7.110
C	0.220	0.245	5.590	6.220
D	0.075	0.095	1.900	2.410
E	0.038	0.058	0.970	1.470
F	-	0.020	-	0.510
G	0.380	0.400	9.640	10.160
H	0.024	0.040	0.610	1.020
I	0.006	0.016	0.150	0.410
J	-	0.050	-	1.270
K	-	0.310	-	7.870
L	-	0.050	-	1.270
M	-	0.125	-	3.170
N	0.002	0.008	0.050	0.200

### Part Numbering System



### Part Marking System



### Packaging

Part number	Component Package	Quantity	Packaging Option	Packaging Specification
SMCGxxxXX-HR	DO-215AB	1500	Tape & Reel – 24mm tape /13" reel	EIA STD RS-481

### Tape and Reel Specification

